

FIG. 1A

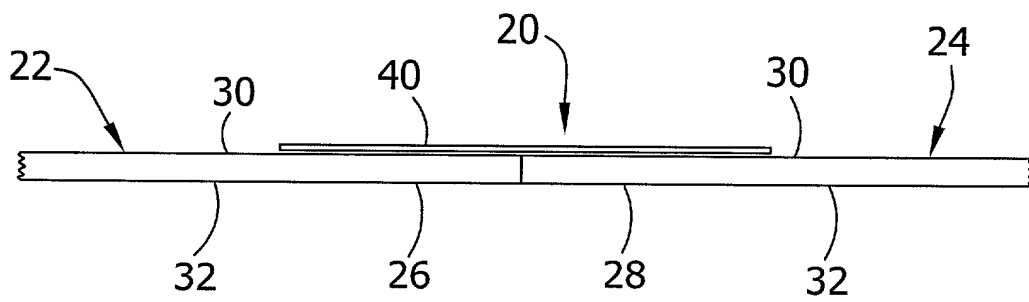


FIG. 1B

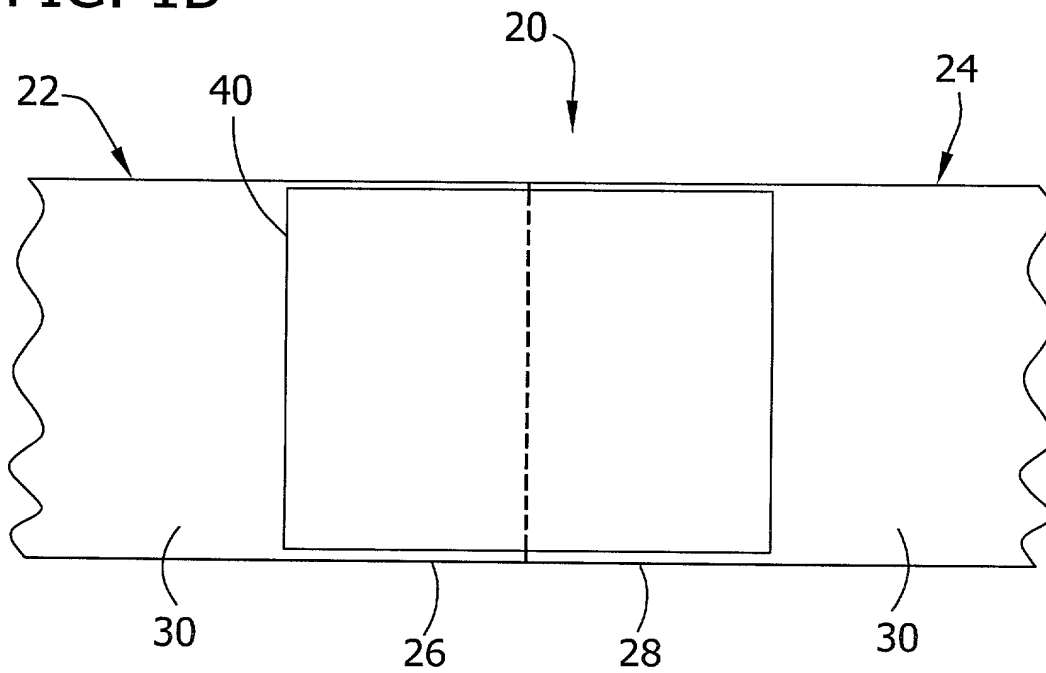


FIG. 2A

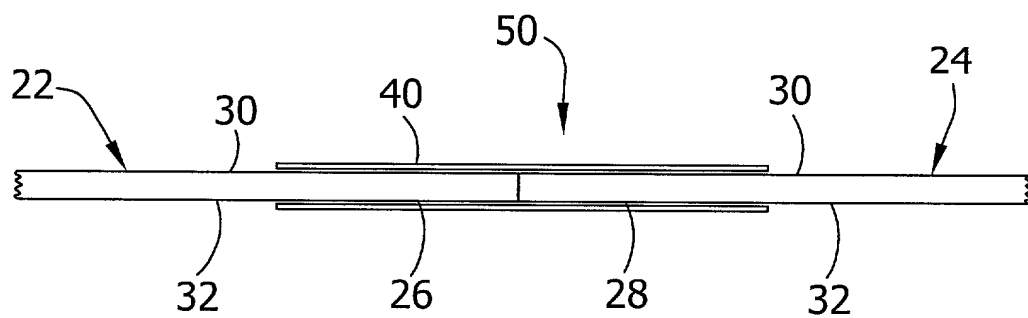


FIG. 2B

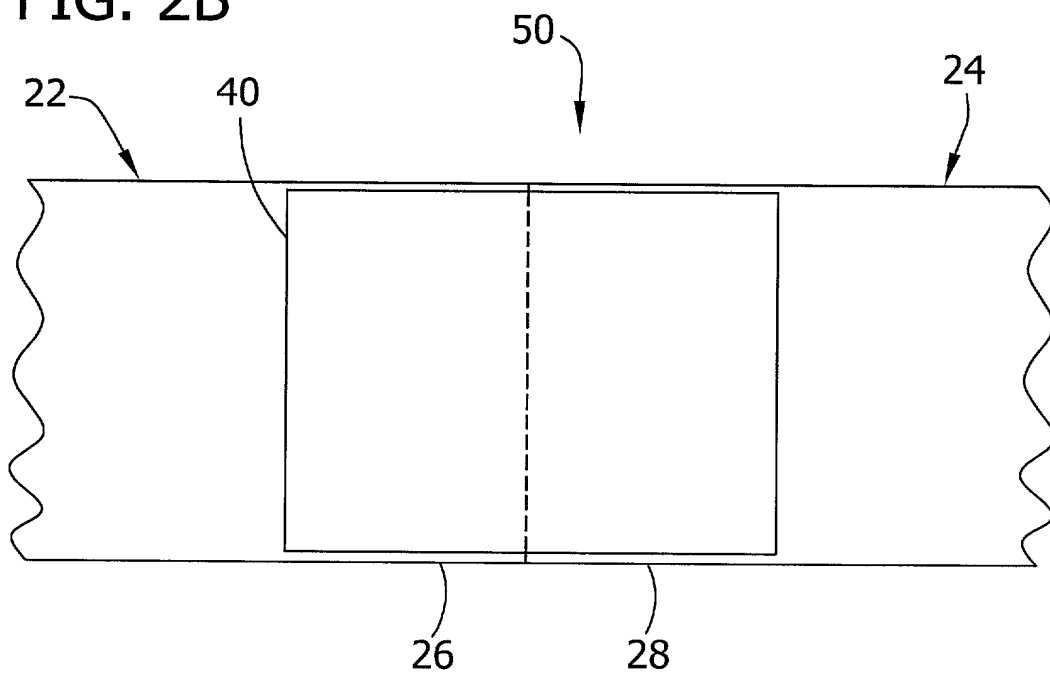


FIG. 3A

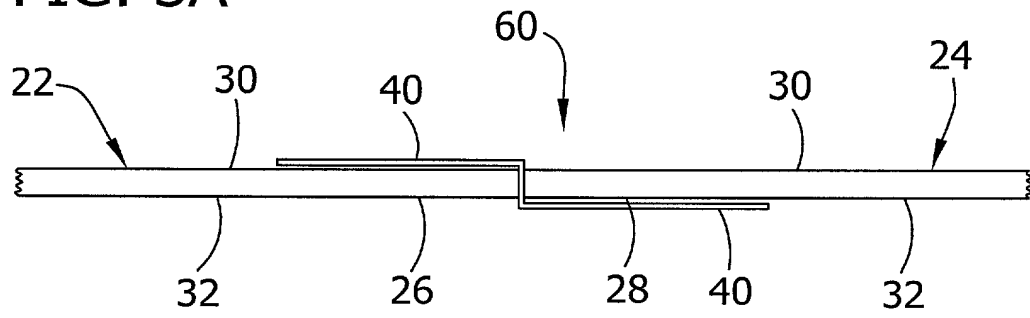


FIG. 3B

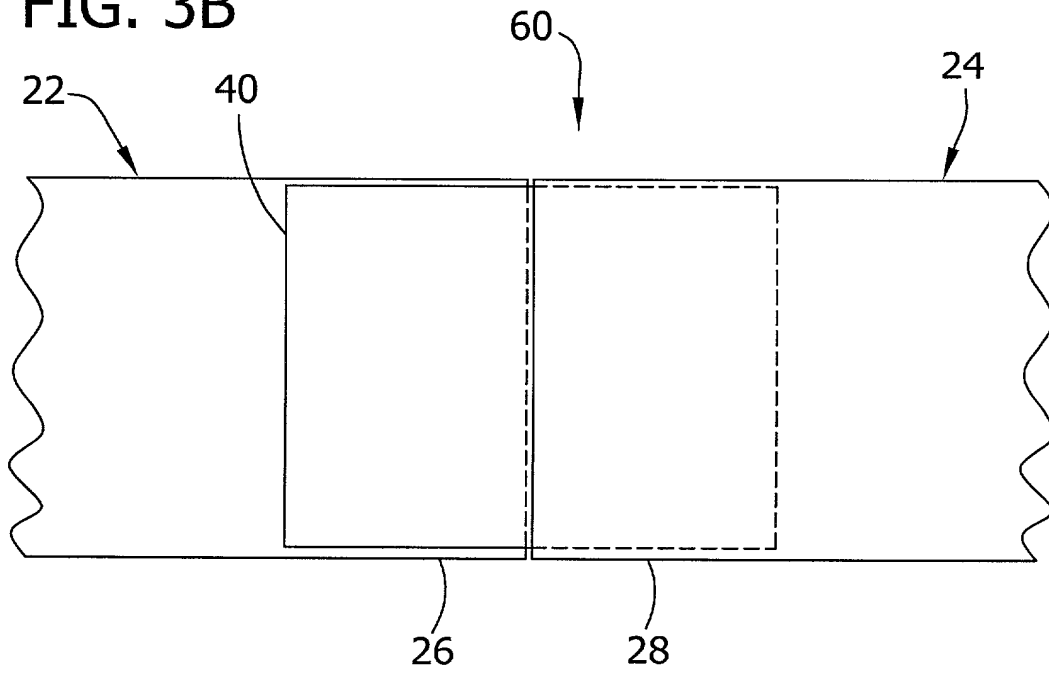


FIG. 4A

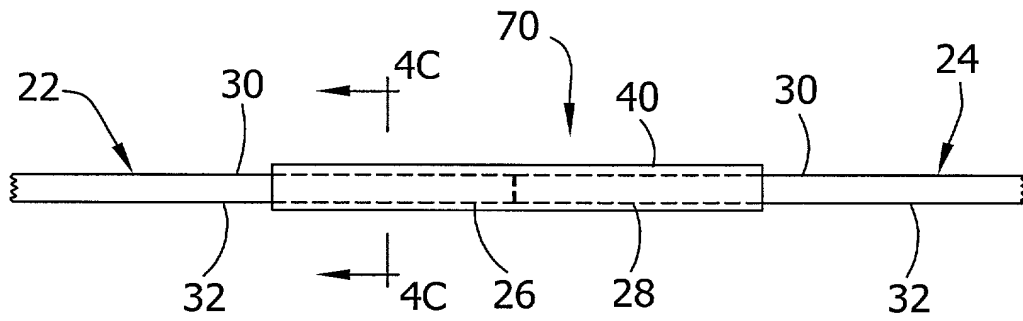


FIG. 4B

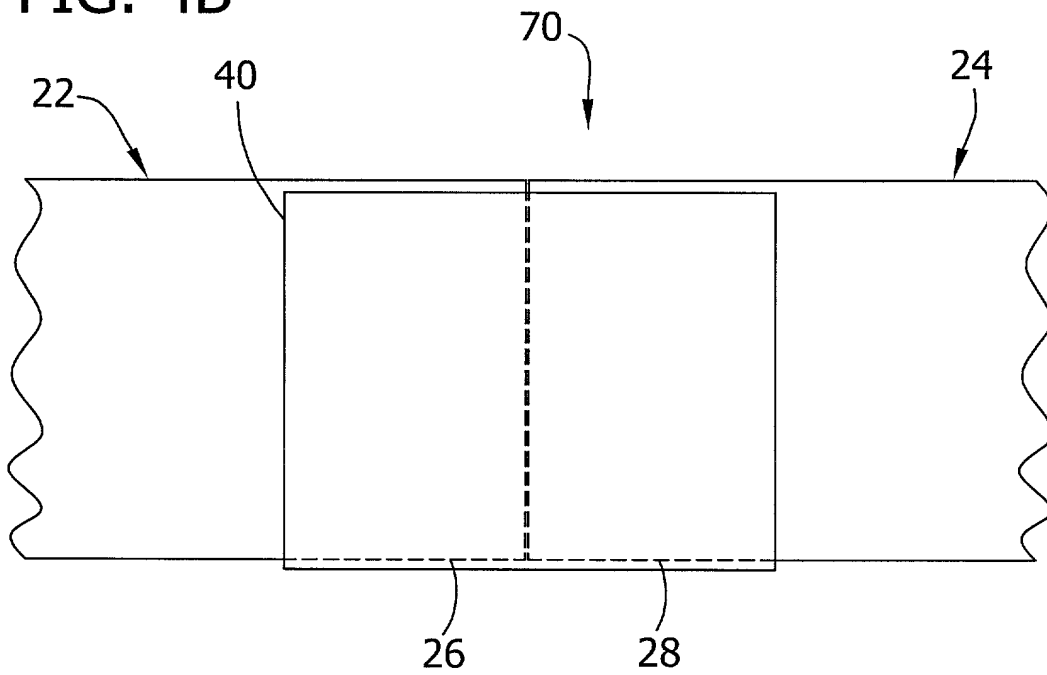


FIG. 4C

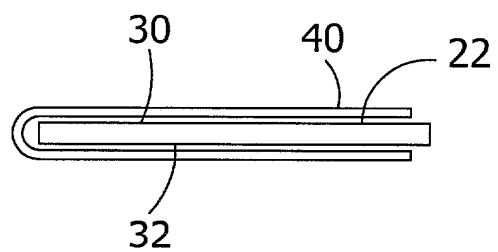


FIG. 5A

FIG. 5A is a schematic cross-sectional view of a device assembly. The assembly includes a substrate 24. A layer 30 is disposed on the top surface of the substrate 24. A layer 32 is disposed on the bottom surface of the substrate 24. A layer 26 is disposed on the top surface of layer 30. A layer 28 is disposed on the top surface of layer 26. A layer 40 is disposed on the top surface of layer 28. A layer 80 is disposed on the top surface of layer 40. A layer 22 is disposed on the left side of the substrate 24.

A cross-sectional view of a substrate 22. A rectangular feature 40 is formed in the substrate. The feature has a dashed inner boundary 80 and a solid outer boundary 24. The substrate is shown with wavy lines on the left and right sides, indicating it is a cross-section of a larger body.

FIG. 6

